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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	S12Z
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, SCI, SPI
Peripherals	DMA, POR, PWM, WDT
Number of I/O	42
Program Memory Size	192KB (192K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 40V
Data Converters	A/D 16x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP Exposed Pad
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s912zvca19f0wkh

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Chapter 1 Device Overview MC9S12ZVC-Family

Chapter 1 Device Overview MC9S12ZVC-Family

1.11.3 Operation of the Secured Microcontroller

By securing the device, unauthorized access to the EEPROM and Flash memory contents is prevented. Secured operation has the following effects on the microcontroller:

1.11.3.1 Normal Single Chip Mode (NS)

- Background debug controller (BDC) operation is completely disabled.
- Execution of Flash and EEPROM commands is restricted (described in flash block description).

1.11.3.2 Special Single Chip Mode (SS)

- Background debug controller (BDC) commands are restricted
- Execution of Flash and EEPROM commands is restricted (described in flash block description).

In special single chip mode the device is in active BDM after reset. In special single chip mode on a secure device, only the BDC mass erase and BDC control and status register commands are possible. BDC access to memory mapped resources is disabled. The BDC can only be used to erase the EEPROM and Flash memory without giving access to their contents.

1.11.4 Unsecuring the Microcontroller

Unsecuring the microcontroller can be done using three different methods:

- 1. Backdoor key access
- 2. Reprogramming the security bits
- 3. Complete memory erase

1.11.4.1 Unsecuring the MCU Using the Backdoor Key Access

In normal single chip mode, security can be temporarily disabled using the backdoor key access method. This method requires that:

- The backdoor key has been programmed to a valid value
- The KEYEN[1:0] bits within the Flash options/security byte select 'enabled'.
- The application program programmed into the microcontroller has the capability to write to the backdoor key locations

The backdoor key values themselves would not normally be stored within the application data, which means the application program would have to be designed to receive the backdoor key values from an external source (e.g. through a serial port)

The backdoor key access method allows debugging of a secured microcontroller without having to erase the Flash This is particularly useful for failure analysis.

NOTE

No backdoor key word is allowed to have the value 0x0000 or 0xFFFF.

Chapter 3 Background Debug Controller (S12ZBDCV2)

3.4.4.12 READ_DBGTB

Read DBG trace buffer

Non-intrusive



This command is only available on devices, where the DBG module includes a trace buffer. Attempted use of this command on devices without a traace buffer return 0x00.

Read 64 bits from the DBG trace buffer. Refer to the DBG module description for more detailed information. If enabled an ACK pulse is generated before each 32-bit longword is ready to be read by the host. After issuing the first ACK a timeout is still possible whilst accessing the second 32-bit longword, since this requires separate internal accesses. The first 32-bit longword corresponds to trace buffer line bits[31:0]; the second to trace buffer line bits[63:32]. If ACK handshaking is disabled, the host must wait 16 clock cycles (DLY) after completing the first 32-bit read before starting the second 32-bit read.

3.4.4.13 READ_SAME.sz, READ_SAME.sz_WS

READ_SAME

Read same location specified by previous READ_MEM{_WS}

Non-intrusive

0x54		Data[15-8]	Data[7-0]
$host \rightarrow target$	D A C K	target \rightarrow host	target \rightarrow host

READ_SAME_WS

Read same location specified by previous READ_MEM{_WS}

Non-intrusive

0x55		BDCCSRL	Data [15-8]	Data [7-0]
$host \rightarrow target$	D L Y	$target \rightarrow host$	target \rightarrow host	target → host

Read from location defined by the previous READ_MEM. The previous READ_MEM command defines the address, subsequent READ_SAME commands return contents of same address. The example shows the sequence for reading a 16-bit word size. Byte alignment details are described in Section 3.4.5.2, "BDC Access Of Device Memory Mapped Resources". If enabled, an ACK pulse is driven before the data bytes are transmitted.

NOTE

When disarming the DBG by clearing ARM with software, the contents of bits[5:0] are not affected by the write, since up until the write operation, ARM = 1 preventing these bits from being written. These bits must be cleared using a second write if required.

Table 6-3. DBGC1 Field Descriptions

Field	Description
7 ARM	 Arm Bit — The ARM bit controls whether the DBG module is armed. This bit can be set and cleared by register writes and is automatically cleared when the state sequencer returns to State0 on completing a debugging session. On setting this bit the state sequencer enters State1. 0 Debugger disarmed. No breakpoint is generated when clearing this bit by software register writes. 1 Debugger armed
6 TRIG	 Immediate Trigger Request Bit — This bit when written to 1 requests an immediate transition to final state independent of comparator status. This bit always reads back a 0. Writing a 0 to this bit has no effect. 0 No effect. 1 Force state sequencer immediately to final state.
4 BDMBP	 Background Debug Mode Enable — This bit determines if a CPU breakpoint causes the system to enter Background Debug Mode (BDM) or initiate a Software Interrupt (SWI). If this bit is set but the BDC is not enabled, then no breakpoints are generated. 0 Breakpoint to Software Interrupt if BDM inactive. Otherwise no breakpoint. 1 Breakpoint to BDM, if BDC enabled. Otherwise no breakpoint.
3 BRKCPU	 CPU Breakpoint Enable — The BRKCPU bit controls whether the debugger requests a breakpoint to CPU upon transitions to State0. Please refer to Section 6.4.5, "Breakpoints for further details. 0 Breakpoints disabled 1 Breakpoints enabled
1 EEVE1	 External Event Enable — The EEVE1 bit enables the external event function. 0 External event function disabled. 1 External event is mapped to the state sequencer, replacing comparator channel 3

6.3.2.2 Debug Control Register2 (DBGC2)

Address: 0x0101





Read: Anytime.

Write: Anytime the module is disarmed.

This register configures the comparators for range matching.

NDB	DBGADM	Comment
0	0	Do not compare data bus bit.
0	1	Compare data bus bit. Match on equivalence.
1	0	Do not compare data bus bit.
1	1	Compare data bus bit. Match on difference.

Table 6-30. NDB and MASK bit dependency

6.4.2.4 Range Comparisons

Range comparisons are accurate to byte boundaries. Thus for data access comparisons a match occurs if at least one byte of the access is in the range (inside range) or outside the range (outside range). For opcode comparisons only the address of the first opcode byte is compared with the range.

When using the AB comparator pair for a range comparison, the data bus can be used for qualification by using the comparator A data and data mask registers. The DBGACTL RW and RWE bits can be used to qualify the range comparison on either a read or a write access. The corresponding DBGBCTL bits are ignored. The DBGACTL COMPE/INST bits are used for range comparisons. The DBGBCTL COMPE/INST bits are ignored in range modes.

6.4.2.4.1 Inside Range (CompA_Addr ≤ address ≤ CompB_Addr)

In the Inside Range comparator mode, comparator pair A and B can be configured for range comparisons by the control register (DBGC2). The match condition requires a simultaneous valid match for both comparators. A match condition on only one comparator is not valid.

6.4.2.4.2 Outside Range (address < CompA_Addr or address > CompB_Addr)

In the Outside Range comparator mode, comparator pair A and B can be configured for range comparisons. A single match condition on either of the comparators is recognized as valid. Outside range mode in combination with opcode address matches can be used to detect if opcodes are from an unexpected range.

NOTE

When configured for data access matches, an outside range match would typically occur at any interrupt vector fetch or register access. This can be avoided by setting the upper or lower range limit to \$FFFFFF or \$000000 respectively. Interrupt vector fetches do not cause opcode address matches.

6.4.3 Events

Events are used as qualifiers for a state sequencer change of state. The state control register for the current state determines the next state for each event. An event can immediately initiate a transition to the next state sequencer state whereby the corresponding flag in DBGSR is set.

- Frequency trimming (A factory trim value for 1MHz is loaded from Flash Memory into the IRCTRIM register after reset, which can be overwritten by application if required)
- Temperature Coefficient (TC) trimming. (A factory trim value is loaded from Flash Memory into the IRCTRIM register to turn off TC trimming after reset. Application can trim the TC if required by overwriting the IRCTRIM register).

Other features of the S12CPMU_UHV_V7 include

- Oscillator clock monitor to detect loss of crystal
- Autonomous periodical interrupt (API)
- Bus Clock Generator
 - Clock switch to select either PLLCLK or external crystal/resonator as source of the Bus Clock
 - PLLCLK divider to adjust system speed
- System Reset generation from the following possible sources:
 - Power-on reset (POR)
 - Low-voltage reset (LVR)
 - COP system watchdog, COP reset on time-out, windowed COP
 - Loss of oscillation (Oscillator clock monitor fail)
 - Loss of PLL clock (PLL clock monitor fail)
 - External pin RESET

Chapter 8 S12 Clock, Reset and Power Management Unit (S12CPMU_UHV_V7)

				RTR[6:4] =			
RTR[3:0]	000 (OFF)	001 (2 ¹⁰)	010 (2 ¹¹)	011 (2 ¹²)	100 (2 ¹³)	101 (2 ¹⁴)	110 (2 ¹⁵)	111 (2 ¹⁶)
0000 (÷1)	OFF ¹	2 ¹⁰	2 ¹¹	2 ¹²	2 ¹³	2 ¹⁴	2 ¹⁵	2 ¹⁶
0001 (÷2)	OFF	2x2 ¹⁰	2x2 ¹¹	2x2 ¹²	2x2 ¹³	2x2 ¹⁴	2x2 ¹⁵	2x2 ¹⁶
0010 (÷3)	OFF	3x2 ¹⁰	3x2 ¹¹	3x2 ¹²	3x2 ¹³	3x2 ¹⁴	3x2 ¹⁵	3x2 ¹⁶
0011 (÷4)	OFF	4x2 ¹⁰	4x2 ¹¹	4x2 ¹²	4x2 ¹³	4x2 ¹⁴	4x2 ¹⁵	4x2 ¹⁶
0100 (÷5)	OFF	5x2 ¹⁰	5x2 ¹¹	5x2 ¹²	5x2 ¹³	5x2 ¹⁴	5x2 ¹⁵	5x2 ¹⁶
0101 (÷6)	OFF	6x2 ¹⁰	6x2 ¹¹	6x2 ¹²	6x2 ¹³	6x2 ¹⁴	6x2 ¹⁵	6x2 ¹⁶
0110 (÷7)	OFF	7x2 ¹⁰	7x2 ¹¹	7x2 ¹²	7x2 ¹³	7x2 ¹⁴	7x2 ¹⁵	7x2 ¹⁶
0111 (÷8)	OFF	8x2 ¹⁰	8x2 ¹¹	8x2 ¹²	8x2 ¹³	8x2 ¹⁴	8x2 ¹⁵	8x2 ¹⁶
1000 (÷9)	OFF	9x2 ¹⁰	9x2 ¹¹	9x2 ¹²	9x2 ¹³	9x2 ¹⁴	9x2 ¹⁵	9x2 ¹⁶
1001 (÷10)	OFF	10x2 ¹⁰	10x2 ¹¹	10x2 ¹²	10x2 ¹³	10x2 ¹⁴	10x2 ¹⁵	10x2 ¹⁶
1010 (÷11)	OFF	11x2 ¹⁰	11x2 ¹¹	11x2 ¹²	11x2 ¹³	11x2 ¹⁴	11x2 ¹⁵	11x2 ¹⁶
1011 (÷12)	OFF	12x2 ¹⁰	12x2 ¹¹	12x2 ¹²	12x2 ¹³	12x2 ¹⁴	12x2 ¹⁵	12x2 ¹⁶
1100 (÷13)	OFF	13x2 ¹⁰	13x2 ¹¹	13x2 ¹²	13x2 ¹³	13x2 ¹⁴	13x2 ¹⁵	13x2 ¹⁶
1101 (÷14)	OFF	14x2 ¹⁰	14x2 ¹¹	14x2 ¹²	14x2 ¹³	14x2 ¹⁴	14x2 ¹⁵	14x2 ¹⁶
1110 (÷15)	OFF	15x2 ¹⁰	15x2 ¹¹	15x2 ¹²	15x2 ¹³	15x2 ¹⁴	15x2 ¹⁵	15x2 ¹⁶
1111 (÷16)	OFF	16x2 ¹⁰	16x2 ¹¹	16x2 ¹²	16x2 ¹³	16x2 ¹⁴	16x2 ¹⁵	16x2 ¹⁶

¹ Denotes the default value out of reset. This value should be used to disable the RTI to ensure future backwards compatibility.





Interrupt	Offset	Vector	Priority	Source	Description
C[7:0]F	—	_	—	Timer Channel 7–0	Active high timer channel interrupts 7–0
PAOVI	—	_	—	Pulse Accumulator Input	Active high pulse accumulator input interrupt
PAOVF	_	_	—	Pulse Accumulator Overflow	Pulse accumulator overflow interrupt
TOF	_	—	—	Timer Overflow	Timer Overflow interrupt

 Table 11-25. TIM16B8CV3 Interrupts

The TIM16B8CV3 could use up to 11 interrupt vectors. The interrupt vector offsets and interrupt numbers are chip dependent.

11.6.1 Channel [7:0] Interrupt (C[7:0]F)

This active high outputs will be asserted by the module to request a timer channel 7-0 interrupt. The TIM block only generates the interrupt and does not service it. Only bits related to implemented channels are valid.

11.6.2 Pulse Accumulator Input Interrupt (PAOVI)

This active high output will be asserted by the module to request a timer pulse accumulator input interrupt. The TIM block only generates the interrupt and does not service it.

11.6.3 Pulse Accumulator Overflow Interrupt (PAOVF)

This active high output will be asserted by the module to request a timer pulse accumulator overflow interrupt. The TIM block only generates the interrupt and does not service it.

11.6.4 Timer Overflow Interrupt (TOF)

This active high output will be asserted by the module to request a timer overflow interrupt. The TIM block only generates the interrupt and does not service it.

Chapter 12 Timer Module (TIM16B4CV3) Block Description

Table 12-1.

V03.00	Jan. 28, 2009		Initial version
V03.01	Aug. 26, 2009	12.1.2/12-388 Figure 1-4./1-8 1.3.2.15/1-18 12.3.2.2/12-391, 1.3.2.3/1-8, Chapter 12/12-38 7, 12.4.3/12-403	 Correct typo: TSCR ->TSCR1; Correct typo: ECTxxx->TIMxxx Correct reference: Figure 1-25 -> Figure 12-22 Add description, "a counter overflow when TTOV[7] is set", to be the condition of channel 7 override event. Phrase the description of OC7M to make it more explicit
V03.02	Apri,12,2010	12.3.2.6/12-394 12.3.2.9/12-396 12.4.3/12-403	-Add Table 1-10 -update TCRE bit description -add Figure 1-31
V03.03	Jan,14,2013		-single source generate different channel guide

12.1 Introduction

The basic scalable timer consists of a 16-bit, software-programmable counter driven by a flexible programmable prescaler.

This timer can be used for many purposes, including input waveform measurements while simultaneously generating an output waveform.

This timer could contain up to 4 input capture/output compare channels. The input capture function is used to detect a selected transition edge and record the time. The output compare function is used for generating output signals or for timer software delays.

A full access for the counter registers or the input capture/output compare registers should take place in one clock cycle. Accessing high byte and low byte separately for all of these registers may not yield the same result as accessing them in one word.

12.1.1 Features

The TIM16B4CV3 includes these distinctive features:

- Up to 4 channels available. (refer to device specification for exact number)
- All channels have same input capture/output compare functionality.
- Clock prescaling.



Figure 13-21. PWM 16-Bit Mode

Once concatenated mode is enabled (CONxx bits set in PWMCTL register), enabling/disabling the corresponding 16-bit PWM channel is controlled by the low order PWMEx bit. In this case, the high order bytes PWMEx bits have no effect and their corresponding PWM output is disabled.

Chapter 18 Scalable Controller Area Network (S12MSCANV3)

18.2 External Signal Description

The MSCAN uses two external pins.

NOTE

On MCUs with an integrated CAN physical interface (transceiver) the MSCAN interface is connected internally to the transceiver interface. In these cases the external availability of signals TXCAN and RXCAN is optional.

18.2.1 RXCAN — CAN Receiver Input Pin

RXCAN is the MSCAN receiver input pin.

18.2.2 TXCAN — **CAN Transmitter Output Pin**

TXCAN is the MSCAN transmitter output pin. The TXCAN output pin represents the logic level on the CAN bus:

- 0 = Dominant state
- 1 =Recessive state

18.2.3 CAN System

A typical CAN system with MSCAN is shown in Figure 18-2. Each CAN station is connected physically to the CAN bus lines through a transceiver device. The transceiver is capable of driving the large current needed for the CAN bus and has current protection against defective CAN or defective stations.



Figure 18-2. CAN System

18.3 Memory Map and Register Definition

This section provides a detailed description of all registers accessible in the MSCAN.

18.3.1 Module Memory Map

Figure 18-3 gives an overview on all registers and their individual bits in the MSCAN memory map. The *register address* results from the addition of *base address* and *address offset*. The *base address* is determined at the MCU level and can be found in the MCU memory map description. The *address offset* is defined at the module level.

The MSCAN occupies 64 bytes in the memory space. The base address of the MSCAN module is determined at the MCU level when the MCU is defined. The register decode map is fixed and begins at the first address of the module address offset.

The detailed register descriptions follow in the order they appear in the register map.

Chapter 22 192 KB Flash Module (S12ZFTMRZ192K2KV2)

Global Address	Size (Bytes)	Field Description
0x1F_C000 - 0x1F_C007	8	Reserved
0x1F_C008 - 0x1F_C0B5	174	Reserved
0x1F_C0B6 - 0x1F_C0B7	2	Version ID ¹
$0x1F_C0B8 - 0x1F_C0BF$	8	Reserved
0x1F_C0C0 - 0x1F_C0FF	64	Program Once Field Refer to Section 22.4.7.6, "Program Once Command"

Table 22-4. Program IFR Fields

¹ Used to track firmware patch versions, see <st-blue>Section 22.4.2 IFR Version ID Word

Table 22-5. Memory Controller Resource Fields (NVM Resource Area¹)

Global Address	Size (Bytes)	Description	
$0x1F_{4000} - 0x1F_{41}FF$	512	Reserved	
$0x1F_4200 - 0x1F_7FFF$	15,872	Reserved	
0x1F_8000 - 0x1F_97FF	6,144	Reserved	
0x1F_9800 - 0x1F_BFFF	10,240	Reserved	
0x1F_C000 - 0x1F_C0FF	256	P-Flash IFR (see Table 22-4)	
0x1F_C100 - 0x1F_C1FF	256	Reserved.	
0x1F_C200 - 0x1F_FFFF	15,872	Reserved.	

¹ See <st-blue>Section 22.4.4 Internal NVM resource for NVM Resources Area description.

Chapter 22 192 KB Flash Module (S12ZFTMRZ192K2KV2)

Protection Update Selection code [1:0]	Protection register selection				
bit 0	Update P-Flash protection 0 - keep unchanged (do not update) 1 - update P-Flash protection with new FPROT value loaded on FCCOB				
bit 1	Update EEPROM protection 0 - keep unchanged (do not update) 1 - update EEPROM protection with new DFPROT value loaded on FCCOB				

Table 22-00. I folection Over flue selection description	Table 22-68.	Protection	Override	selection	description
--	--------------	------------	----------	-----------	-------------

If the comparison key successfully matches the key programmed in the Flash Configuration Field the Protection Override command will preserve the current values of registers FPROT and DFPROT stored in an internal area and will override these registers as selected by the Protection Update Selection field with the value(s) loaded on FCCOB parameters. The new values loaded into FPROT and/or DFPROT can reconfigure protection without any restriction (by increasing, decreasing or disabling protection limits). If the command executes successfully the FPSTAT FPOVRD bit will set.

If the comparison key does not match the key programmed in the Flash Configuration Field, or if the key loaded on FCCOB is 16'hFFFF, the value of registers FPROT and DFPROT will be restored to their original contents before executing the Protection Override command and the FPSTAT FPOVRD bit will be cleared. If the contents of the Protection Override Comparison Key in the Flash Configuration Field is left in the erased state (i.e. 16'hFFFF) the Protection Override feature is permanently disabled. If the command execution is flagged as an error (ACCERR being set for incorrect command launch) the values of FPROT and DFPROT will not be modified.

The Protection Override command can be called multiple times and every time it is launched it will preserve the current values of registers FPROT and DFPROT in a single-entry buffer to be restored later; when the Protection Override command is launched to restore FPROT and DFPROT these registers will assume the values they had before executing the Protection Override command on the last time. If contents of FPROT and/or DFPROT registers were modified by direct register writes while protection is overrideen these modifications will be lost. Running Protection Override command to restore the contents of registers FPROT and DFPROT will not force them to the reset values.

A.1.7 **Power Dissipation and Thermal Characteristics**

Power dissipation and thermal characteristics are closely related. The user must assure that the maximum operating junction temperature is not exceeded. The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_{J} = T_{A} + (P_{D} \bullet \Theta_{JA})$$

 T_{I} = Junction Temperature, [°C]

 $T_A = Ambient Temperature, [°C]$

 P_{D} = Total Chip Power Dissipation, [W]

 Θ_{IA} = Package Thermal Resistance, [°C/W]

The total power dissipation P_D can be calculated from the equation below. Table A-6 below lists the power dissipation components. Table A-6 gives an overview of the supply currents.

 $P_{D} = P_{VSUP} + P_{BCTL} + P_{INT} - P_{GPIO} + P_{CANPHY}$

Power Component	Description
$P_{VSUP} = V_{SUP} I_{SUP}$	Internal Power through VSUP pin
$P_{BCTL} = V_{BCTL} I_{BCTL}$	Internal Power through BCTL pin
$P_{INT} = V_{DDX} I_{VDDX} + V_{DDA} I_{VDDA}$	Internal Power through VDDX/A pins.
$P_{GPIO} = V_{I/O} I_{I/O}$	Power dissipation of external load driven by GPIO Port. Assuming the load is connected between GPIO and ground. This power component is included in P_{INT} and is subtracted from overall MCU power dissipation P_D
$P_{CANPHY} = [V_{DDC} - (V_{CANH} - V_{CANL})] I_{VDDC}$	Power dissipation of CANPHY

Table A-6. Power Dissipation Components





In Figure D-5. the timing diagram for slave mode with transmission format CPHA=1 is depicted.



Figure D-5. SPI Slave Timing (CPHA=1)





N.10 0x0500-0x052F PWM1

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
0x050C PWMCNT0	PWMCNTO	R	Bit 7	6	5	4	3	2	1	Bit 0
	W	0	0	0	0	0	0	0	0	
0x050D PWMCNT1	R	Bit 7	6	5	4	3	2	1	Bit 0	
	W	0	0	0	0	0	0	0	0	
0.0505		R	Bit 7	6	5	4	3	2	1	Bit 0
0x050E	PWMCN12	W	0	0	0	0	0	0	0	0
0.0505		R	Bit 7	6	5	4	3	2	1	Bit 0
0x050F	PWMCN13	w	0	0	0	0	0	0	0	0
0.0510		R	Bit 7	6	5	4	3	2	1	Bit 0
0x0510	PWMCN14	W	0	0	0	0	0	0	0	0
0.0511		R	Bit 7	6	5	4	3	2	1	Bit 0
0x0511	PWMCN15	W	0	0	0	0	0	0	0	0
0.0510		R	Bit 7	6	5	4	3	2	1	Bit 0
0x0512	PWMCN16	W	0	0	0	0	0	0	0	0
0.0510		R	Bit 7	6	5	4	3	2	1	Bit 0
0x0513	PWMCN17	W	0	0	0	0	0	0	0	0
0x0514	PWMPER0	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x0515	PWMPER1	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x0516	PWMPER2	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x0517	PWMPER3	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x0518	PWMPER4	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x0519	PWMPER5	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x051A	PWMPER6	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x051B	PWMPER7	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x051C	PWMDTY0	R W	Bit 7	6	5	4	3	2	1	Bit 0

N.12 0x0600-0x063F ADC0 (continued)

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0	
0x0608	ADC0EiF	R W	IA_EIF	CMD_EIF	EOL_EIF	Reserved	TRIG_EIF	RSTAR_EI F	LDOK_EIF	0	
0x0609	ADC0IF	R W	SEQAD_IF	CONIF_OI	Reserved	0	0	0	0	0	
0x060A	ADC0CONIE_0	R W		CON_IE[15:8]							
0x060B	ADC0CONIE_1	R W		CON_IE[7:1] EOI							
0x060C	ADC0CONIF_0	R W		CON_IF[15:8]							
0x060D	ADC0CONIF_1	R W		CON_IF[7:1] EC							
0x060E	ADC0IMDRI_0	R	CSL_IMD	RVL_IMD	0	0	0	0	0	0	
0x060F	ADC0IMDRI_1	R W	0	0 RIDX_IMD							
0x0610	ADC0EOLRI	R W	CSL_EOL	RVL_EOL	0	0	0	0	0	0	
0x0611	Reserved	R W	0	0	0	0	0	0	0	0	
0x0612	Reserved	R W	0	0	0	0	0	0	0	0	
0x0613	Reserved	R W	Reserved 0								
0x0614	ADC0CMD_0	R W	CMD_SEL 0 0 INTFLG_SEL[3:0]								
0x0615	ADC0CMD_1	R W	VRH_SEL	VRH_SEL VRL_SEL CH_SEL[5:0]							
0x0616	ADC0CMD_2	R W	SMP[4:0] 0 0 R							Reserved	
0x0617	ADC0CMD_3	R W	Reserved	Reserved Reserved							
0x0618	Reserved	R W	Reserved								
0x0619	Reserved	R W	Reserved								
0x061A	Reserved	R W	Reserved								
0x061B	Reserved	R W		Reserved							
0x061C	ADC0CIDX	R W	0 0 CMD_IDX[5:0]								
0x061D	ADC0CBP_0	R W	CMD_PTR[23:16]								
0x061E	ADC0CBP_1	R W	CMD_PTR[15:8]								
0x061F	ADC0CBP_2	R W	CMD_PTR[7:2] 0						0	0	